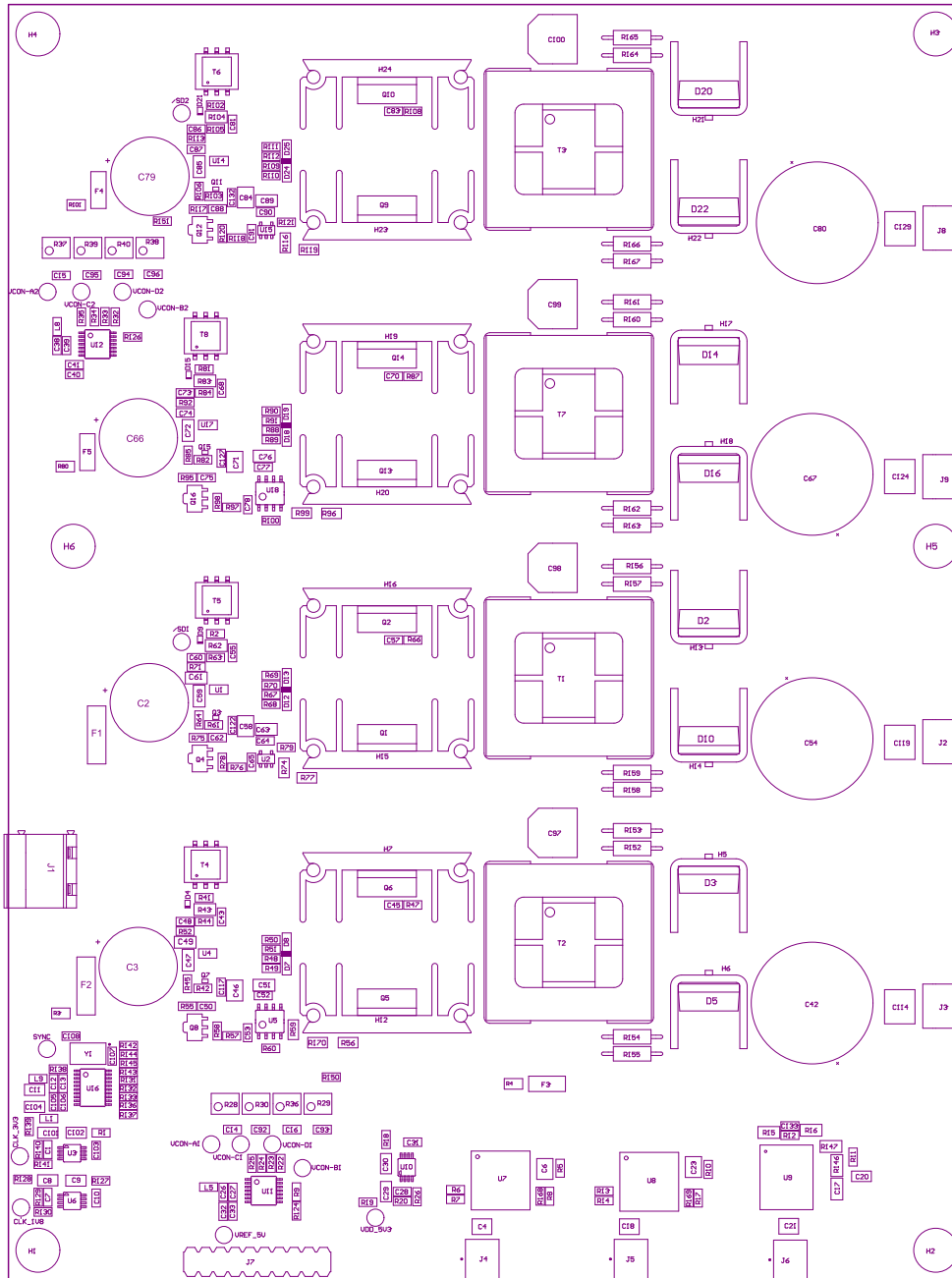
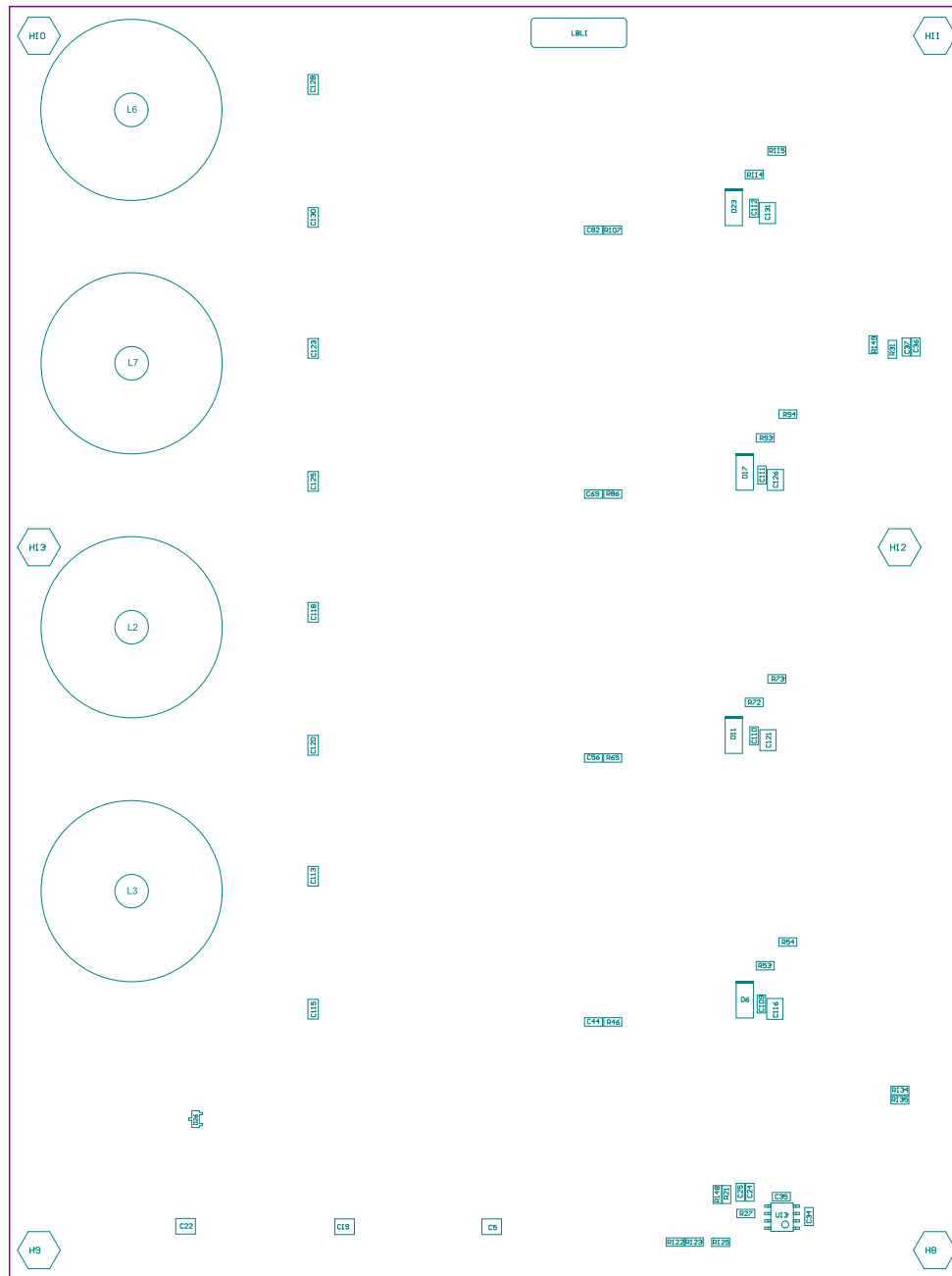


Z28 ■ Install Label in silkscreened box after final test. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 Z29 ■ These assemblies are ESD sensitive. ESD precautions shall be observed.
 Z210 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z211 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANTS: (No Variations)

PCB VIEWED FROM TOP SIDE	BOARD #:	TIDN-01362	REV:	E2	SUN REV:	Not In VersionControl
LAYER NAME =	PS Assembly Top	TID #:	TIDN-01362			
PLDT NAME =	Top Assembly Drawing	GENERATED	19-06-2017	14:44:16		TEXAS INSTRUMENTS



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANTS: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOMID #: T1DA-01362	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M6 Assembly Bottom	TID #: T1DA-01362 IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED: 19-06-2017	14:44:17	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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